## 5 é / Descriptions

SOD-123 .> / / x l 9 8 â ’ož

Zener Diode in a SOD-123 Plastic Package.

## ¤ ª / Features

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500mW power dissipation, medium current, automated assembly processes, HF Product.

## Ð ÷ / Applications

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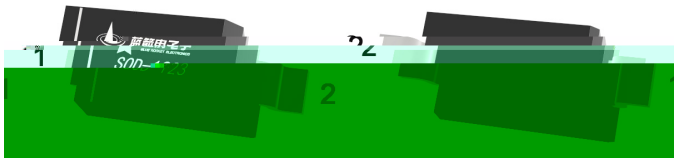
2.4V to 39V wide zener voltage range applications.




PIN1:Cathode PIN2:Anode

## , M V / Marking

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See Marking Instructions.

| @ *f*<br>Parameter | … Z<br>Symbol | *f* ›<br>Rating | % y<br>Unit |
|---|---|---|---|
| Forward Voltage (Note 2) $I_F$=10mA | $V_F$ | 0.9 | V |
| Power Dissipation(Note 1) | $P_D$ | 500 | mW |
| Typical Thermal Resistance Junction to Ambient(Note 1) | R $_{JA}$ | 305 | /W |
| Junction and Storage Temperature Range | $T_j$,$T_{stg}$ | -65 150 | |

| Type Number | Mark-ing Code | Zener Voltage Range | | | | Maximum Zener Impedance | | | Maximum Reverse Current | |
|---|---|---|---|---|---|---|---|---|---|---|
| | | $V_z$ @$I_{ZT}$ | | | $I_{ZT}$ | $Z_{ZT}$ @$I_{ZT}$ | $Z_{ZK}$ @$I_{ZK}$ | $I_{ZK}$ | $I_R$ | @$V_R$ |
| | | Nom (V) | Min (V) | Max (V) | mA | | | mA | A | V |

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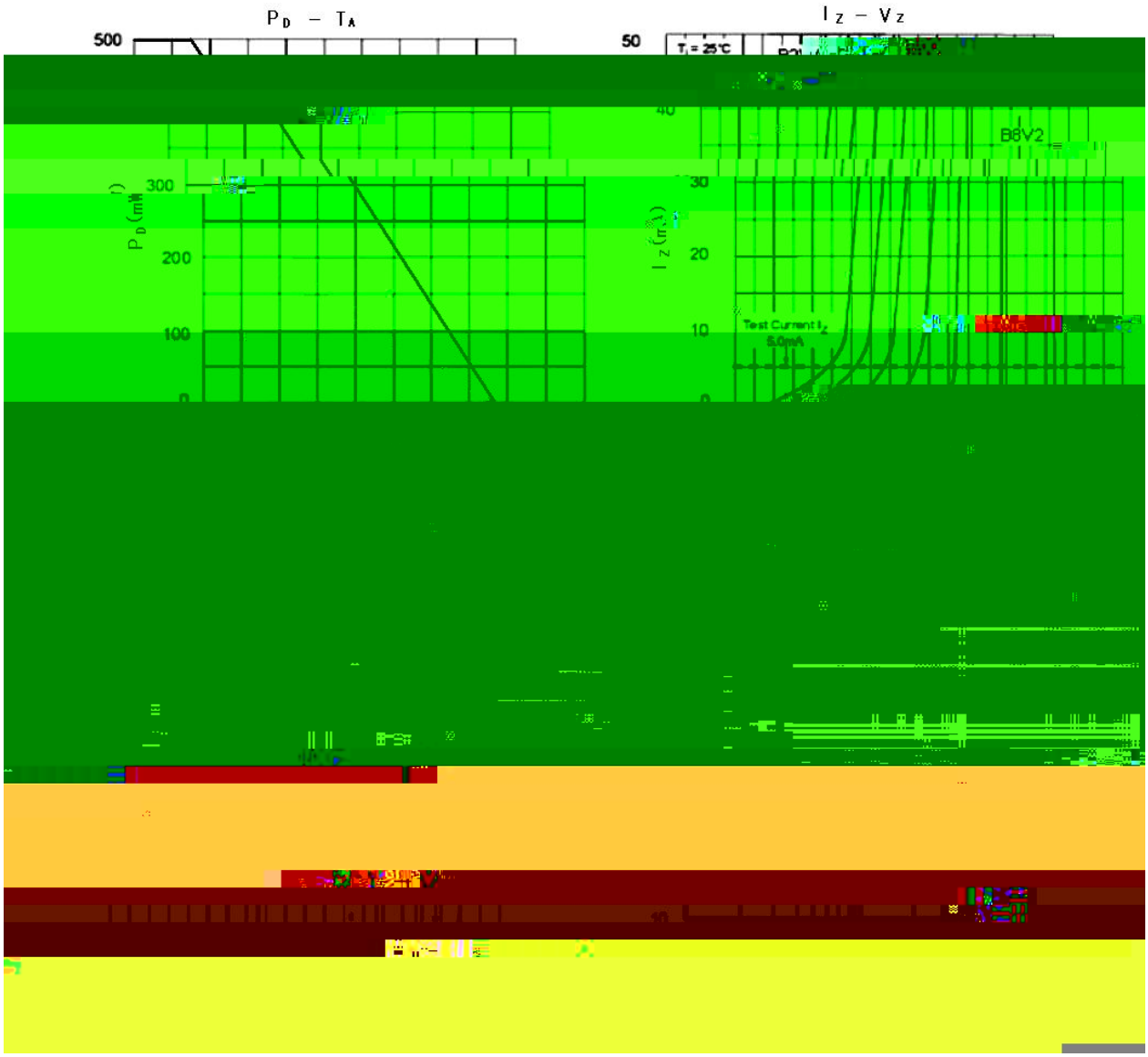
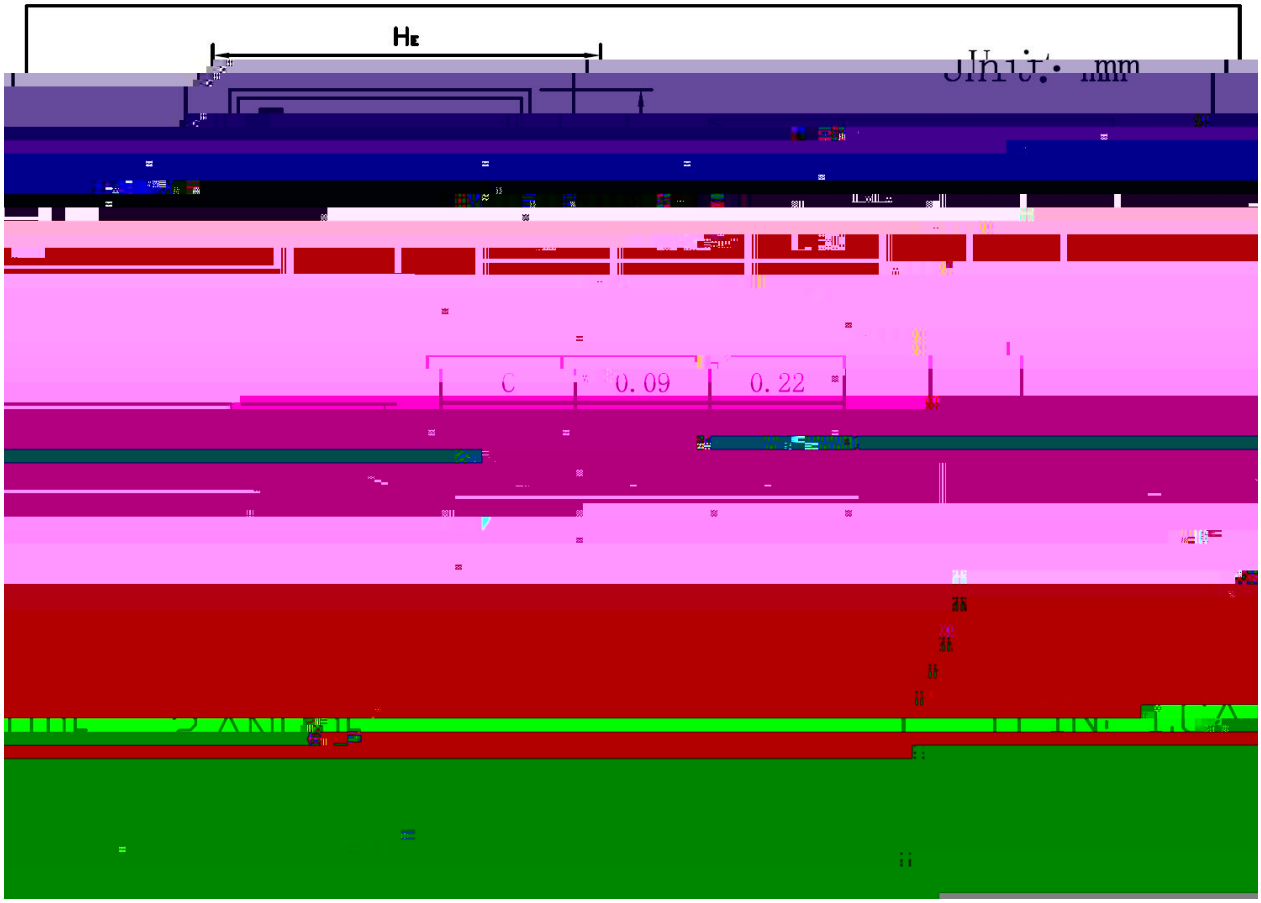
Notes:

1. Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad areas 25mm$^2$.
2. Short duration test pulse used to minimize self-heating effect.
3. f = 1kHz.

## Ô ? d • Ž ¢ / Electrical Characteristic Curve



## Ø ¤ = ) ¢ / Package Dimensions



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## š WD t … • Ž ¢ ( x / ) / : K S V K X G Z [ X K 6 X U L O R K L U X / 8 8 K L R U ] 9 U R J K X O T M 6

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1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;

2o• Q › “ † 245 r 5 - k ž • 4 Ò 5 r 0.5sec;

3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r 5 - , Duration:5 r 0.5sec.

3. Cooling Speed: 2~10 - /sec.

## ÂD /Cã p ¯ » ] / Resistance to Soldering Heat Test Conditions

“ † y 260 r 5 - ž • y 10 r 1 sec. Temp.:260±5 Time:10±1 sec

## G P á / Packaging SPEC.

2 & x / REEL

| Package Type 7>û ˜ E | Units ;>û ¦H | Dimension ;>û p . (unit ÆEmm³) |
|---|---|---|